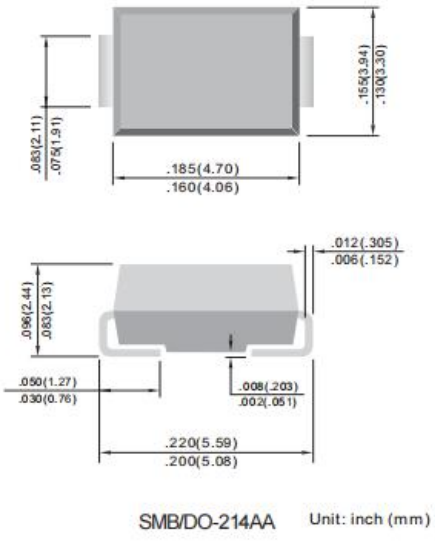
Surface Mount General Rectifier

VOLTAGE- 50 to 1000 Volts CURRENT - 2.0 Ampere



SMB/DO-214AA Unit: inch (mm)

FEATURES

The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
For surface mounted applications
Low reverse leakage
Built-in strain relief,ideal for automated placement
High forward surge current capability
High temperature soldering guaranteed:
250 C/10 seconds at terminals

MECHANICALDATA

Case: JEDEC DO-214AA molded plastic
Terminals: Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight :0.0035 ounce, 0.098 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS @T_A=25°C unless otherwise specified

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	GS2A	GS2B	GS2D	GS2G	GS2J	GS2K	GS2M	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at T_L=110 C	$I_{(AV)}$	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50.0							Amps
Maximum instantaneous forward voltage at 2.0A	V_F	1.1							Volts
Maximum DC reverse current T_A=25 C at rated DC blocking voltage T_A=100 C	I_R	5.0 50.0							∝A
Typical junction capacitance (NOTE 1)	C_J	30.0							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	85.0							°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150							℃

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2″(5.0x5.0mm) copper pad areas

RATING AND CHARCTERISTIC CURVES

FIG. 1- FORWARD CURRENT DERATING CURVE

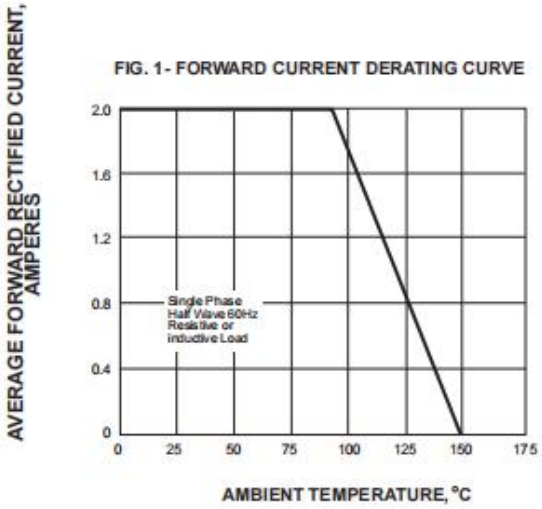


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

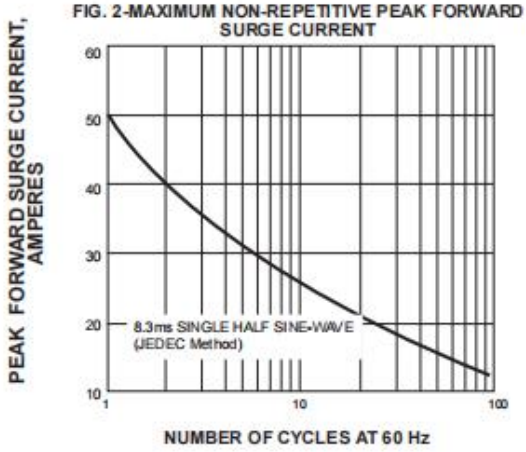


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

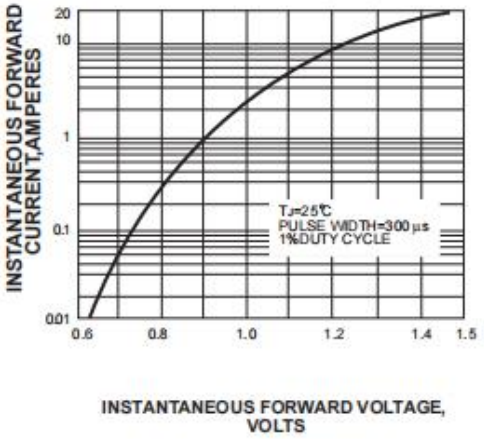
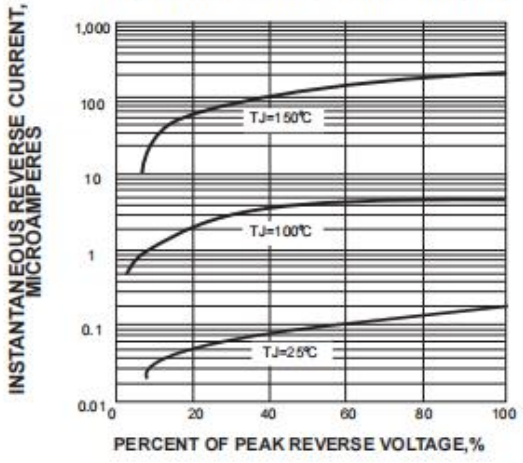
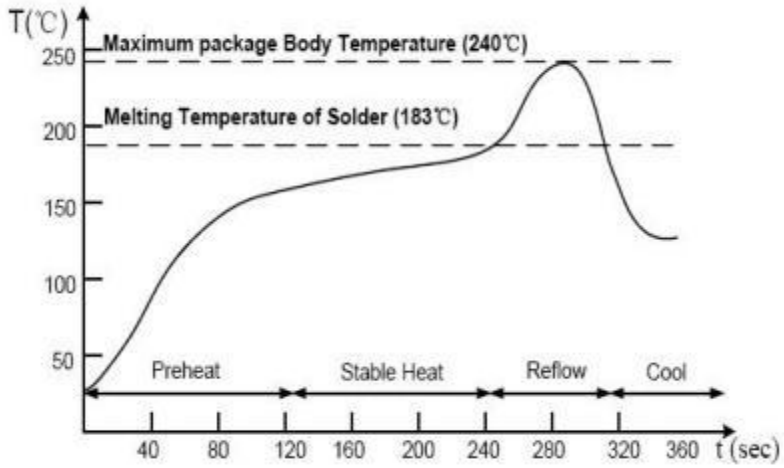


FIG. 4-TYPICAL REVERSE CHARACTERISTICS



Suggested Soldering Temperature Profile

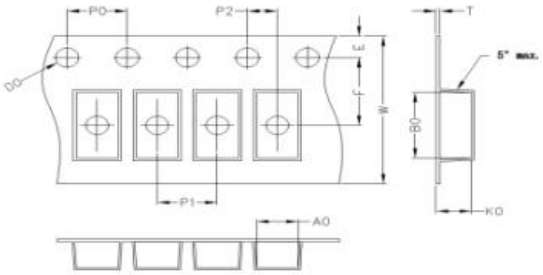


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265 °C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
3.80	5.40	2.45	1.55	1.75	5.50
P0	**P1**	**P2**	**T**	**W**	**Tolerance**
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMB	13'	330	3.0	340	6.0	360*360*360	48